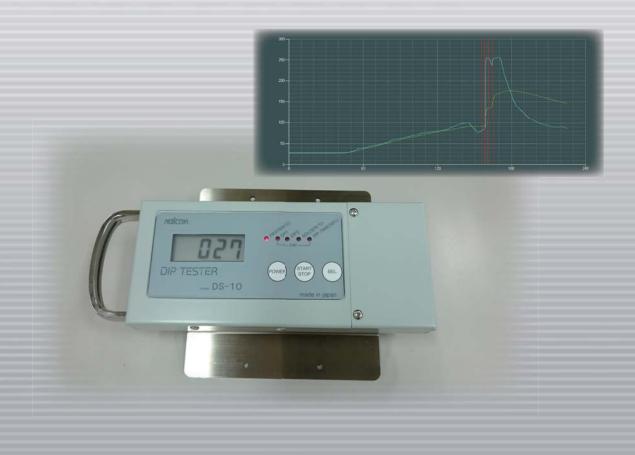
## DS-10

## **DIP TESTER**

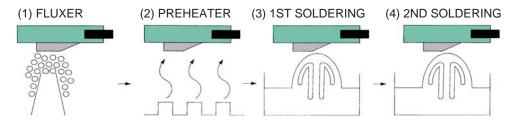


- Data transmission to a PC by USB cable, creating a profile function.
- Dedicated software realizes high level of management.

## **DS-10 DIP TESTER**

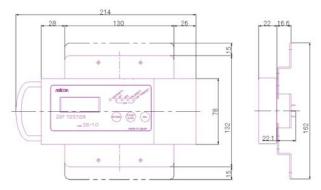
Putting it a conveyor to flow through a solder bath to obtain information needed to manage it.

- USB connection to a PC, the dedicated software enables for OK/NG judgment and the management of the test results.
- The created temperature profile makes it possible to monitor the 50ms sampling temperature of the preheat and solder temperature sensors in addition to the conventional management items.
- The heat-resistant cover for high heat load such as Nitrogen oven and etc. is available as an option.
- Equipped with a New Dip Time Sensor, providig a more accurate measurement.



Measurement Data Specifications						
Items	Sensor	Display	Measurement range	Accuracy	OK/NG judgment	
Prehdat temp.	CA thermocouple	Digital LCD 3-digit	50~300°C	±1°C	PC software	
Solder temp.	CA sheath thermocouple		0~300°C	±1°C		
Dip timie (1st · 2nd)	Electrode (4pcs.)		0~10sec.	±0.2sec.		
Temp. profile	Preheat · Solder temp.	PC software	0~300°C	±1°C	_	
General Specifications						

Items	Speifications		
Cold contact point compensation	Compensation with platinum temp. measuring resistor		
Heatresistant temp.	150 °C, 5 minutes		
Display	LCD		
External connection	USB (mini B connector)		
Number of memories	1		
Sampling time	50 ms (fix)		
Outer dimensions • Weight	214 (D) mm x 78 (W) mm 43.6 (H) mm •820g		
Power supply	AAA batteries x 3pcs. (Ni-MH rechargeable battery is also available.)		



The above specifications are subject to change without notice.

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